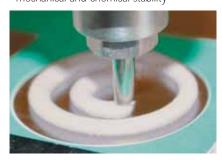
# Gap Filler 1000 (Two-Part)

Thermally Conductive, Liquid Gap Filling Material

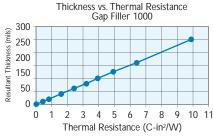
#### **Features and Benefits**

- Thermal conductivity: 1.0 W/m-K
- Ultra-conforming, designed for fragile and low-stress applications
- Ambient and accelerated cure schedules
- 100% solids no cure by-products
- Excellent low and high temperature mechanical and chemical stability



Gap Filler 1000 is a thermally conductive, liquid gap filling material. It is supplied as a twocomponent, room or elevated temperature curing system. The material is formulated to provide a balance of cured material properties highlighted by a low modulus and good compression set (memory). The result is a soft, thermally conductive, form-in-place elastomer ideal for coupling "hot" electronic components mounted on PC boards with an adjacent metal case or heat sink. Before cure, Gap Filler 1000 flows under pressure like a grease. After cure, it does not pump from the interface as a result of thermal cycling. Unlike thermal grease, the cured product is dry to the touch. Unlike cured gap filling materials, the liquid approach offers infinite thickness with little or no stress during displacement and eliminates the need for specific pad thickness and die-cut shapes for individual applications. Gap Filler 1000 is intended for use in thermal interface applications when a strong structural bond is not required.

Note: Resultant thickness is defined as the final gap thickness of the application.



#### **TYPICAL PROPERTIES OF GAP FILLER 1000** PROPERTY IMPERIAL VALUE METRIC VALUE TEST METHOD Color / Part A Gray Gray Visual Color / Part B White White Visual Viscosity as Mixed (cps) (1) 100.000 100.000 **ASTM D2196** Density (g/cc) 1.6 1.6 ASTM D792 Mix Ratio 1.1 1.1 Shelf Life @ 25°C (months) 6 6 PROPERTY AS CURED Gray Gray Visual Hardness (Shore 00) (2) 30 30 ASTM D2240 Heat Capacity (J/g-K) 1.0 1.0 ASTM E1269 -76 to 347 Continuous Use Temp (°F) / (°C) -60 to 175 **ELECTRICAL AS CURED** Dielectric Strength (V/mil) 500 500 ASTM D149 Dielectric Constant (1000 Hz) 5.0 5.0 ASTM D150 Volume Resistivity (Ohm-meter) 10<sup>1</sup> 10<sup>1</sup> ASTM D257 Flame Rating V-O V-O U.L. 94 THERMAL AS CURED Thermal Conductivity (W/m-K) 1.0 1.0 ASTM D5470 **CURE SCHEDULE** Pot Life @ 25°C (min) (3) 15 15 Cure @ 25°C (min) (4) 60 - 120 60 - 120 Cure @ 100°C (min) (4) 5

- 1) Brookfield RV, Heli-Path, Spindle TF @ 20 rpm, 25°C
- 2) Thirty second delay value Shore 00 hardness scale
- 3) Time for viscosity to double.
- 4) Cure schedule (rheometer time to read 90% cure)

### Typical Applications Include:

Automotive electronics

- Telecommunications
- Computer and peripherals
- Thermally conductive vibration dampening

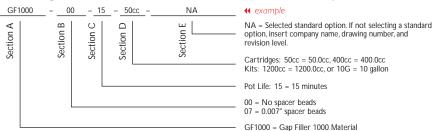
**Standard Options** 

• Between any heat-generating semiconductor and a heat sink

#### **Configurations Available:**

• Supplied in cartridge and kit form

#### **Building a Part Number**



Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others

## BERGOUIST

www.bergquistcompany.com

The Bergquist Company European Headquarters The Bergquist Company -North American Headquarters 18930 West 78th Street Chanhassen, MN 55317 Phone: 800-347-4572 Bramenberg 9a, 3755 BT Eemnes Netherlands Phone: 31-35-5380684 Fax: 31-35-5380295 Fax: 952-835-0430

The Bergquist Company - Asia No. 38-40, Au Pui Wan Street Fotan, Shatin, N.T. Hong Kong Ph: 852 2690.294 Fax: 852.2690.2344 All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN LIEU OF ALL WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MARKETABILITY AND FITNESS FOR PURPOSE. Sellers' and manufacturers' only obligation shall be to replace such quantity of the product proved to be defective. Before using user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whatsoever in connection therewith. NETHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER INTORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE, DIRECT, INCIDENTAL, OR CONSEQUENTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARSING OUT OF THE USE OR THE INABILITYTO USE A PRODUCT. No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer.

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